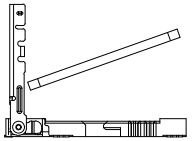
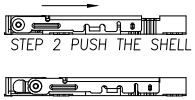
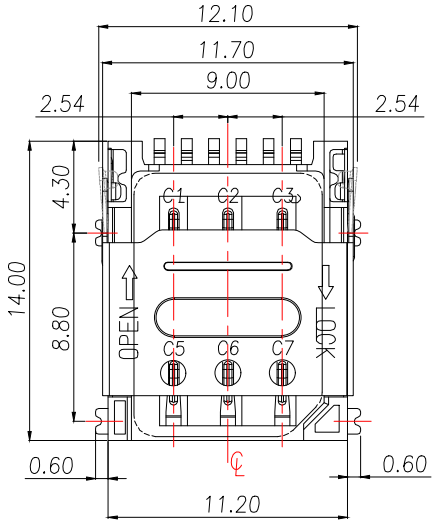
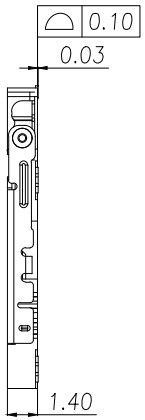
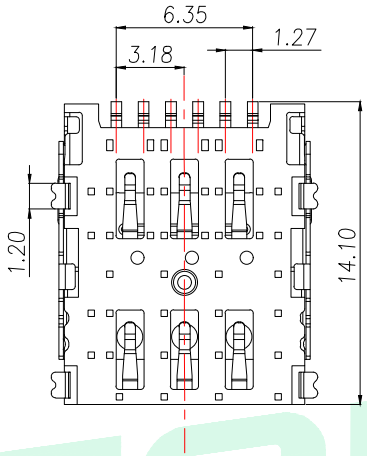
REV.	DESCRIPTION	ECN NO.	NAME	DATE

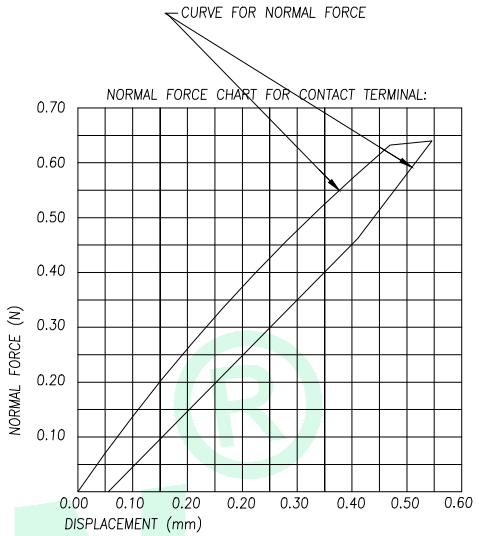


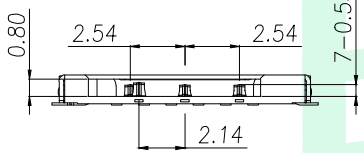


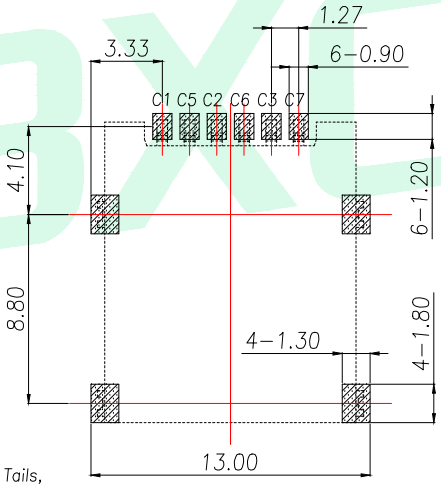


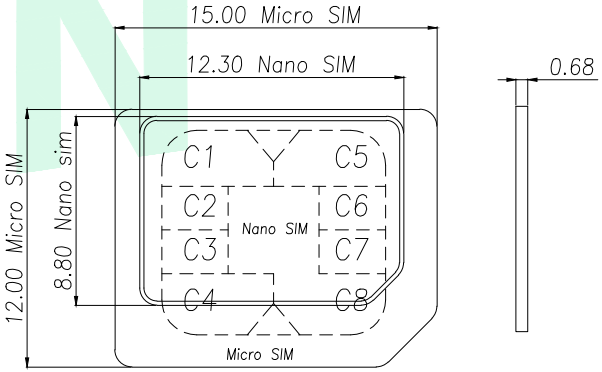












NANO SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A

NOTES:

1.MATERIAL:
- 1.1 Housing:High Temperature Thermoplastic UL94V-0; Color Black.
- 1.2 Terminal:Copper Alloy,T=0.12mm.
- 1.3 Shell:Stainless Steel,T=0.20mm.

2.FINISH:
- 2.1 Terminal:Plated Gold on The Contact Area and Solder Tails
- 2.2 Peg:Plated Gold on the bottom of the Solder Tails, Tin Plated over all.

3.SPECIALITY:
- 3.1 Rated current:0.5A
- 3.2 Rated voltage:50V
- 3.3 Contact Resistance:80mΩMAX
- 3.4 Insulation Resistance:100MΩMIN 100V DC
- 3.5 Dielectric withstanding voltage: 100V AC.
- 3.6 Solder ability:245±5°C,5±0.5s.
- 3.7 Operating condition:Temperature: -40°C~+85°C Humidity: 80% R.H MAX

PAD AREA

KEEP OUT AREA

RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE ±0.05

NO.	PART NAME	Q'TY	DESCRIPTION	NOTE
3	TERMINAL	6	C5210-EH,T=0.12	G/F PLATING
2	BASE INSULATOR	1	LCP+GF30%	BLACK
1	SHELL	1	SUS304-H,T=0.15	AU/Ni PLATING

GENERAL TOLERANCE		
DIM.	TOL.	
x.	±0.50	
x.x	±0.20	
x.xx	±0.10	
GENERAL ANGLE:		
x.°	±2°	
x.x°	±1°	

DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD

BXCONN®

TITLE: 6PIN 1.4H HINGE NANO SIM CARD CONN.

DWG. NO.: SIM-301A-GZ6P

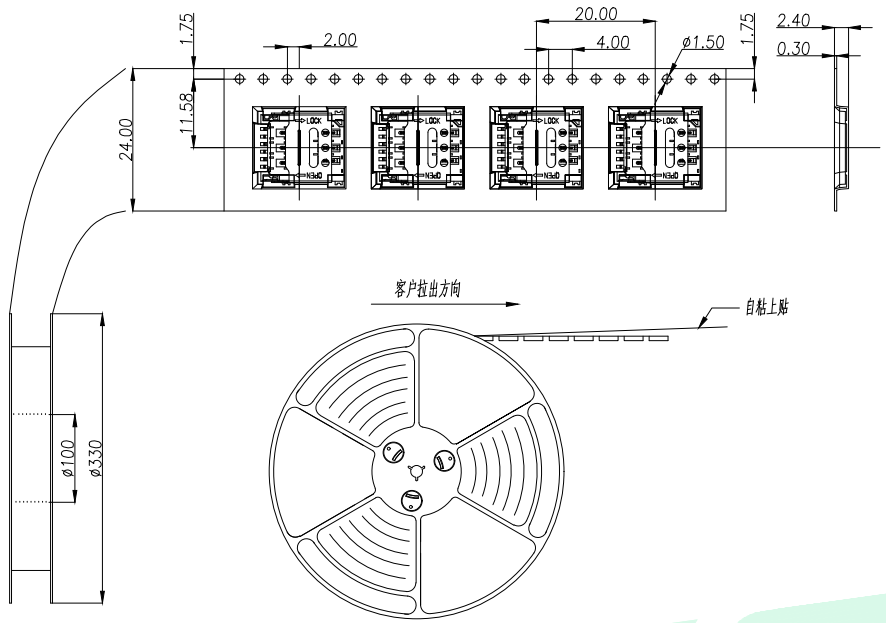
CHECKED: MAX

PART NO.: SIM-301A-GZ6P

DRAWN: ELLA

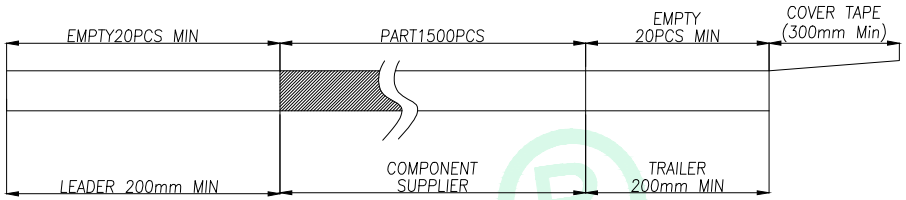
UNIT:	SCALE:	SHEET:	DWG. SIZE:	LAYER:	APPROVED:
mm	none	1of 2	A4	bxconn	WILL

REV.	DESCRIPTION	ECN NO.	NAME	DATE

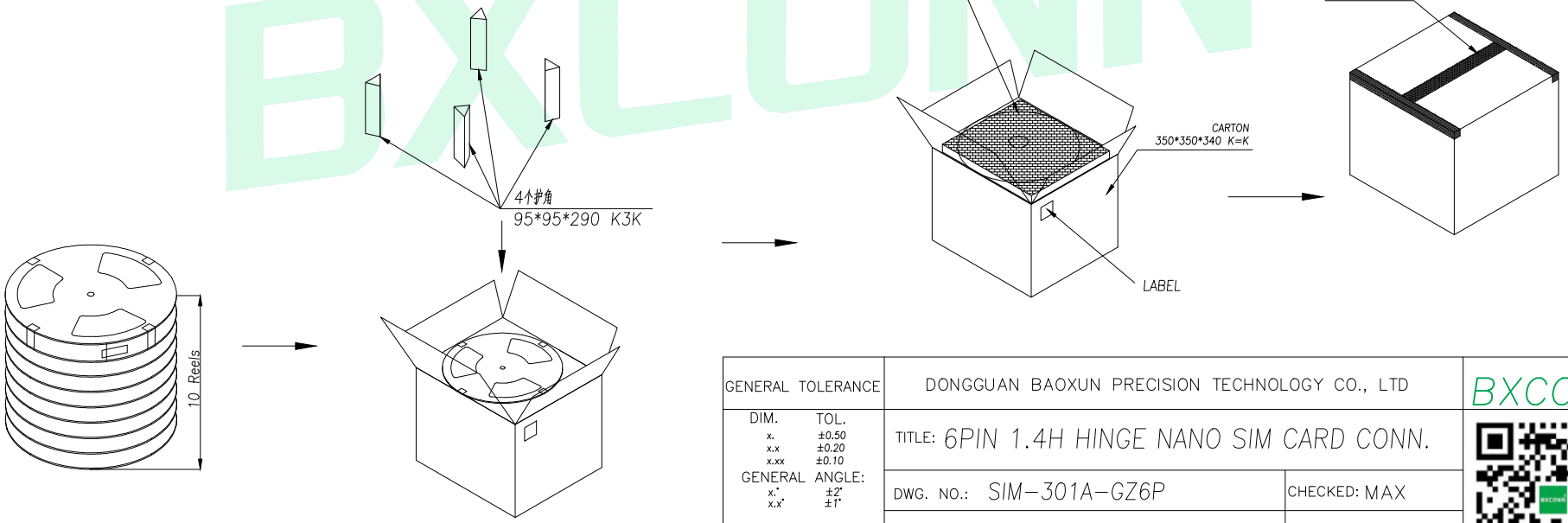


NOTES

1. NUMBER OF CONNECTORS:1500PCS/REEL
2. LEAD TAPE LENGTH



3.QUANTITY:15000PCS/CARTON



GENERAL TOLERANCE	DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD					BXCONN®
DIM. TOL. x. ±0.50 x.x ±0.20 x.xx ±0.10 GENERAL ANGLE: x.° ±2° x.x° ±1°	TITLE: 6PIN 1.4H HINGE NANO SIM CARD CONN.					
	DWG. NO.: SIM-301A-GZ6P				CHECKED: MAX	
	PART NO.: SIM-301A-GZ6P				DRAWN: ELLA	
	UNIT: mm	SCALE: none	SHEET: 2of 2	DWG. SIZE: A4	LAYER: bxconn	APPROVED: WILL